

## ENGINEERING DEPT. REVISIONS ECNT120078

## **PRODUCT SPECIFICATION** For CF20 Series Connector System

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1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and inserted on the specified size FPC and FFC

## 2. APPLICABLE STANDARDS:

| MIL - STD - 202 | Methods for test of connectors for electronic equipment              |
|-----------------|--|
| EAI – 364       | Test methods for electrical connectors                               |
| J-STD-020       | Resistance to soldering Temperature for through hole Mounted Devices |
| SS-00254        | Test methods for electronic components, LEAD-FREE soldering Part     |
|                 | design standards   |

- 3. APPLICABLE SERIES NO .: CF20\*\*\*\*\*\*-NH
- 4. SHAPE, CONSTRUCTION AND DIMENSIONS See attached drawings
- 5. MATERIALS See attached drawings
- 6. ACCOMMODATED P.C.BOARD6.1 Thickness: 0.5 mm (.020") ~ 2.0 mm (.079")6.2 P.C. Board Layout: See attached drawings
- 7. ACCOMMODATED FPC/FFC THICKNESS 0.3 +0.04/-0.01 mm (.012+.002/-.001")



REVIEWED : <u>Eisley</u> APPROVED : <u>Sun</u> VERIFIED : <u>Eric</u>.



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| . ELF               | . ELECTRICAL PERFORMANCE:           |            |                                  |  |   |       |                             |  |
|                     | IT                                  | EM         |                                  | TEST CONDITION   | REQUIREMENT   |       |                             |  |
| 8.1                 | Rated cur<br>voltage                | rent and   |                                  |  | 0.4A max.<br>50V AC/DC max.                           |       | IX.                         |  |
| 8.2                 | Contact re                          | esistance  | Dry<br>max                       | circuit of DC 20 mV max., 100 mA   | Less than 30 m $\Omega$                               |       | 2                           |  |
| 8.3                 | Dielectric                          | strength   |                                  | en applied AC 250 V 1 minute between cent terminal                                     | No change   |       |                             |  |
| 8.4                 | Insulation                          | resistance |                                  | en applied DC 500 V between adjacent inal or ground                                    | More than   | 100 1 | MΩ                          |  |
| . ME                | CHANICA                             | L PERFOR   | MAN                              | CE:  |   |       |                             |  |
|                     | IT                                  | EM         |                                  | TEST CONDITION   | REQ   | UIRE  | EMENT                       |  |
| 9.1                 | Contact re<br>force in in           | 0          | Rete<br>hous                     | ention speed $25 \pm 3$ mm per minute from sing  | More than 0.2 Kgf(1.96N)                              |       | Kgf(1.96N)                  |  |
| 9.2                 | FFC / FPC<br>withdrawa<br>(Referenc | al force   |                                  | sure force to withdrawal using 0.30 mm<br>kness FPC / FFC at speed 25± 3 mm per<br>ate | Standard:<br>(0.02× no.<br>min.<br>(0.196× no<br>min. |       | ontacts) Kgf<br>Contacts) N |  |
| 9.3                 | Separation slider and               |            |                                  | out the slider from the base at speed 3 mm per minute                                  | More than 2.0 Kgf(19.6N)                              |       | Ggf(19.6N)                  |  |
| 9.4                 | Durability                          | 7          |                                  | nector shall be subjected to 20 cycles of rtion and withdrawal                         | Contact res<br>Less than t                            |       |                             |  |

## 10. ENVIRONMENTAL PERFORMANCE:

|      | ITEM             | TEST CONDITION  | REQUIREMENT  |
|------|------------------|---|--|
| 10.1 | Temperature rise | Then carried the rated current                                      | 30°C max.  |
| 10.2 | Vibration        | 1.5 mm 10-55-10 HZ / minute each 2 hours for X, Y and Z directions  | Appearance: No damage<br>Discontinuity:<br>1 micro second max. |
| 10.3 | Solder ability   | Soldering time: $3 \pm 0.5$ second<br>Soldering pot: $245 \pm 5$ °C | Minimum:<br>90% of immersed area                               |



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|                   |                              |                                       |  |   |                |   |  |
|                   | ITEM TE                      |                                       | TES                                    | TEST CONDITION  |                | EQUIREMENT  |  |
| 10.4              | Resistance to soldering heat |                                       | Refer Reflow temperature profile(12.1) |   | No damage      |   |  |
|                   |                              |                                       | Sold                                   | ering time: 20 second Max. Soldering  |                |   |  |
|                   |                              |                                       | pot:                                   | 250~260°C   |                |   |  |
| 10.5              | Heat aging                   | g                                     | 85 ±                                   | 2°C, 96 hours   | No             | o damage  |  |
| 10.6              | Humidity                     |                                       | meas                                   | 2°C, 90-95% RH, 96 hours<br>surement must be taken within 30 min.<br>tested   | Co<br>Le<br>Di | ppearance: No damage<br>ontact resistance:<br>ess than twice of initial<br>ielectric strength:<br>o pass para 8-3 |  |
| 10.7              | Temperature cycling          |                                       | One                                    | cycle consists of :   | A              | ppearance: No damage  |  |
|                   |                              |                                       | (1)-                                   | $55^{+0}_{-3}$ °C , 30 min.   | Co             | ontact resistance:  |  |
|                   |                              |                                       | (2)R                                   | oom temp. 10-15 min.  | Le             | ess than twice of initial   |  |
|                   |                              |                                       | (3) 8                                  | $85_{-0}^{+3}$ °C, 30 min.  |                |   |  |
|                   |                              |                                       |  | oom temp. 10-15 min.  |                |   |  |
| 10.8              | Salt spray                   | ,                                     | Tem                                    | perature: $35 \pm 3^{\circ}C$   | A              | ppearance: No damage  |  |
|                   |                              |                                       | Solu                                   | tion: $5 \pm 1\%$   | Co             | ontact resistance:  |  |
|                   |                              |                                       | Spra                                   | y time: $48 \pm 4$ hours  | Le             | ess than twice of initial   |  |
|                   |                              |                                       | (Star                                  | nping before plated)  |                |   |  |
|                   |                              |                                       | Spra                                   | y time: $24 \pm 4$ hours  |                |   |  |
|                   |                              |                                       | (Star                                  | nping after plated)   |                |   |  |
|                   |                              |                                       | salt r<br>expo<br>remo<br>wate         | e connectors and expose to the following<br>mist conditions. Upon completion of the<br>osure period, salt deposits shall be<br>oved by a gentle wash or dip in running<br>or and dried naturally, after which the<br>ified measurements shall be performed. |                |   |  |
|                   |                              |                                       | top u<br>threa                         |   |                |   |  |
|                   |                              |                                       | platin<br>not b                        | test only define the plating area, without<br>ng area (as copper cross section) will<br>be defined.   |                |   |  |
|                   |                              |                                       | (EIA                                   | 364-26B / MIL-STD-202 Method 101)   |                |   |  |



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11. AMBIENT TEMPERATURE RANGE: -25 to + 85°C12. Recommended IR Reflow Temperature Profile:

12.1 Using Lead-Free Solder Paste

